



March 1997  
Revised March 1999

## 74VHCT245A Octal Buffer/Line Driver with 3-STATE Outputs

### General Description

The VHCT245A is an advanced high speed CMOS octal bus transceiver fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. The VHCT245A is intended for bidirectional asynchronous communication between data busses. The direction of data transmission is determined by the level of the T/R input. The enable input can be used to disable the device so that the busses are effectively isolated. Protection circuits ensure that 0V to 7V can be applied to the input and output (Note 1) pins without regard to the

supply voltage. These circuits prevent device destruction due to mismatched supply and input/output voltages. This device can be used to interface 5V to 3V systems and two supply systems such as battery back up.

**Note 1:** Outputs in OFF-State

### Features

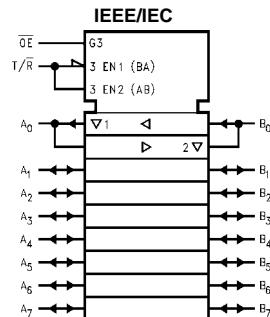
- High Speed:  $t_{PD} = 5.4$  ns (typ) at  $V_{CC} = 5V$
- Power Down Protection on Inputs and Outputs
- Low Power Dissipation:  $I_{CC} = 4 \mu A$  (Max) @  $T_A = 25^\circ C$
- Pin and Function Compatible with 74HCT245

### Ordering Code:

Order Number	Package Number	Package Description
74VHCT245AM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74VHCT245ASJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHCT245AMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74VHCT245AN	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

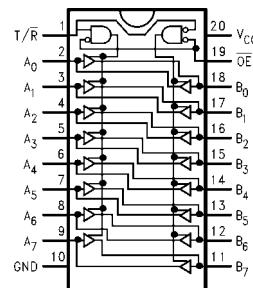
### Logic Symbol



### Pin Descriptions

Pin Names	Description
OE	Output Enable Input
T/R	Transmit/Receive Input
A <sub>0</sub> -A <sub>7</sub>	Side A Inputs or 3-STATE Outputs
B <sub>0</sub> -B <sub>7</sub>	Side B Inputs or 3-STATE Outputs

### Connection Diagram



### Truth Table

Inputs	Outputs	
	OE	T/R
L	L	Bus B Data to Bus A
L	H	Bus A Data to Bus B
H	X	HIGH-Z State

H = HIGH Voltage Level  
L = LOW Voltage Level  
X = Immaterial

74VHCT245A

Absolute Maximum Ratings <sup>(Note 2)</sup>				Recommended Operating Conditions <sup>(Note 6)</sup>				
Supply Voltage ( $V_{CC}$ )		-0.5V to +7.0V		Supply Voltage ( $V_{CC}$ )		4.5V to +5.5V		
DC Input Voltage ( $V_{IN}$ )		-0.5V to +7.0V		Input Voltage ( $V_{IN}$ )		0V to +5.5V		
DC Output Voltage ( $V_{OUT}$ )				Output Voltage ( $V_{OUT}$ )				
(Note 3)		-0.5V to $V_{CC}$ + 0.5V		(Note 3)		0V to $V_{CC}$		
(Note 4)		-0.5V to +7.0V		(Note 4)		0V to +5.5V		
Input Diode Current ( $I_{IK}$ )		-20 mA		Operating Temperature ( $T_{OPR}$ )		-40°C to +85°C		
Output Diode Current ( $I_{OK}$ ) (Note 5)		±20 mA		Input Rise and Fall Time ( $t_r, t_f$ )				
DC Output Current ( $I_{OUT}$ )		±25 mA		$V_{CC} = 5.0V \pm 0.5V$		0 ns/V ~ 20 ns/V		
DC $V_{CC}$ /GND Current ( $I_{CC}$ )		±75 mA						
Storage Temperature ( $T_{STG}$ )		-65°C to +150°C						
Lead Temperature ( $T_L$ )								
(Soldering, 10 seconds)		260°C						
<b>Note 2:</b> Absolute Maximum Ratings are values beyond which the device may be damaged or have its useful life impaired. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation outside databook specifications.								
<b>Note 3:</b> HIGH or LOW state. $I_{OUT}$ absolute maximum rating must be observed.								
<b>Note 4:</b> When outputs are in OFF-State or when $V_{CC} = 0V$ .								
<b>Note 5:</b> $V_{OUT} < GND$ , $V_{OUT} > V_{CC}$ (Outputs Active).								
<b>Note 6:</b> Unused inputs must be held HIGH or LOW. They may not float.								
DC Electrical Characteristics								
Symbol	Parameter	$V_{CC}$ (V)	$T_A = 25^\circ C$		$T_A = -40^\circ C$ to $+85^\circ C$		Units	Conditions
			Min	Typ	Max	Min		
$V_{IH}$	HIGH Level Input Voltage	4.5	2.0		2.0		V	
		5.5	2.0		2.0			
$V_{IL}$	LOW Level Input Voltage	4.5		0.8		0.8	V	
		5.5		0.8		0.8		
$V_{OH}$	HIGH Level Output Voltage	4.5	4.40	4.50	4.40		V	$V_{IN} = V_{IH}$ or $V_{IL}$ $I_{OH} = -50 \mu A$ $I_{OH} = -8 mA$
		3.94		3.80				
$V_{OL}$	LOW Level Output Voltage	4.5	0.0	0.1	0.1		V	$V_{IN} = V_{IH}$ or $V_{IL}$ $I_{OL} = 50 \mu A$ $I_{OL} = 8 mA$
			0.36		0.44			
$I_{OZ}$	3-STATE Output Off-State Current	5.5		±0.25		±2.5	$\mu A$	$V_{IN} = V_{IH}$ or $V_{IL}$ $V_{OUT} = V_{CC}$ or GND
$I_{IN}$	Input Leakage Current	0–5.5		±0.1		±1.0	$\mu A$	$V_{IN} = 5.5V$ or GND
$I_{CC}$	Quiescent Supply Current	5.5		4.0		40.0	$\mu A$	$V_{IN} = V_{CC}$ or GND
$I_{CCT}$	Maximum $I_{CC}$ /Input	5.5		1.35		1.50	$mA$	$V_{IN} = 3.4V$ Other Input = $V_{CC}$ or GND
$I_{OFF}$	Output Leakage Current (Power Down State)	0.0		0.5		5.0	$\mu A$	$V_{OUT} = 5.5V$

Noise Characteristics						
Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C		Units	Conditions
			Typ	Limits		
V <sub>OLP</sub> (Note 7)	Quiet Output Maximum Dynamic V <sub>OL</sub>	5.0	1.2	1.6	V	C <sub>L</sub> = 50 pF
V <sub>OLV</sub> (Note 7)	Quiet Output Minimum Dynamic V <sub>OL</sub>	5.0	-1.2	-1.6	V	C <sub>L</sub> = 50 pF
V <sub>IHD</sub> (Note 7)	Minimum HIGH Level Dynamic Input Voltage	5.0		2.0	V	C <sub>L</sub> = 50 pF
V <sub>ILD</sub> (Note 7)	Maximum LOW Level Dynamic Input Voltage	5.0		0.8	V	C <sub>L</sub> = 50 pF

Note 7: Parameter guaranteed by design.

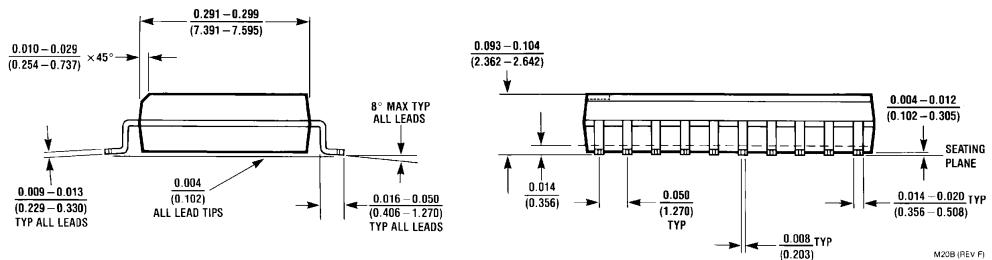
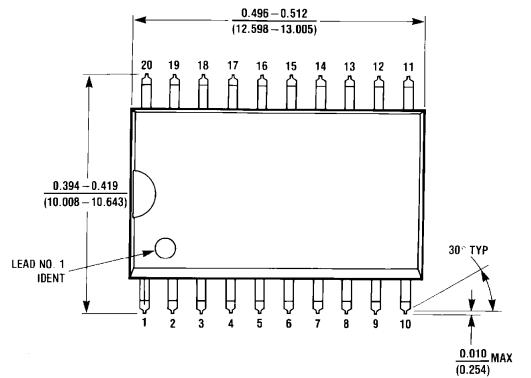
AC Electrical Characteristics						
Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40°C to +85°C	
			Min	Typ	Max	Min
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay Time	5.0 ± 0.5	4.9	7.7	1.0	8.5
			5.4	8.7	1.0	9.5
t <sub>PZL</sub> t <sub>PZH</sub>	3-STATE Output Enable Time	5.0 ± 0.5	9.4	13.8	1.0	15.0
			9.9	14.8	1.0	16.0
t <sub>PLZ</sub> t <sub>PHZ</sub>	3-STATE Output Disable Time	5.0 ± 0.5	10.1	15.4	1.0	16.5
t <sub>OSLH</sub> t <sub>OSHL</sub>	Output to Output Skew	5.0 ± 0.5		1.0		1.0
C <sub>IN</sub>	Input Capacitance		4	10		10
C <sub>OUT</sub>	Output Capacitance		13			
C <sub>PD</sub>	Power Dissipation Capacitance		16			16

Note 8: Parameter guaranteed by design. t<sub>OSLH</sub> = |t<sub>PLH</sub> max - t<sub>PLH</sub> min|; t<sub>OSHL</sub> = |t<sub>PHL</sub> max - t<sub>PHL</sub> min|

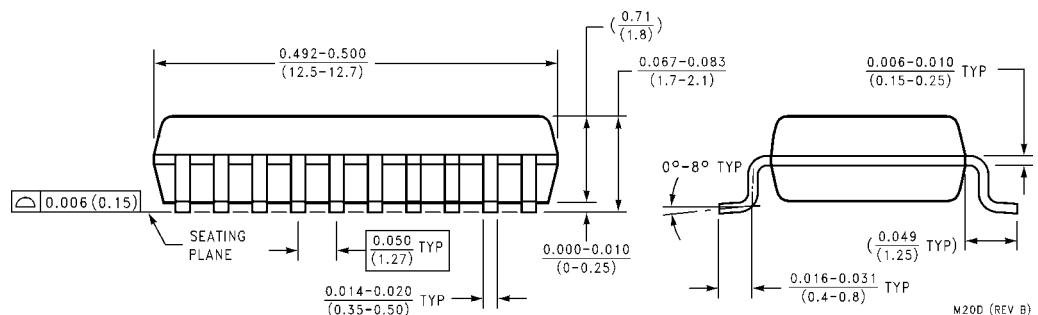
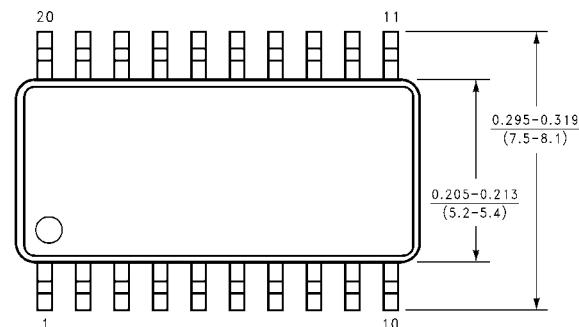
Note 9: C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC</sub> (opr) = C<sub>PD</sub> \* V<sub>CC</sub> \* f<sub>IN</sub> + I<sub>CC</sub>/8 (per F/F). The total C<sub>PD</sub> when n pcs. of the Octal D Flip-Flop operates can be calculated by the equation: C<sub>PD</sub> (total) = 20 + 12n.

74VHCT245A

**Physical Dimensions** inches (millimeters) unless otherwise noted

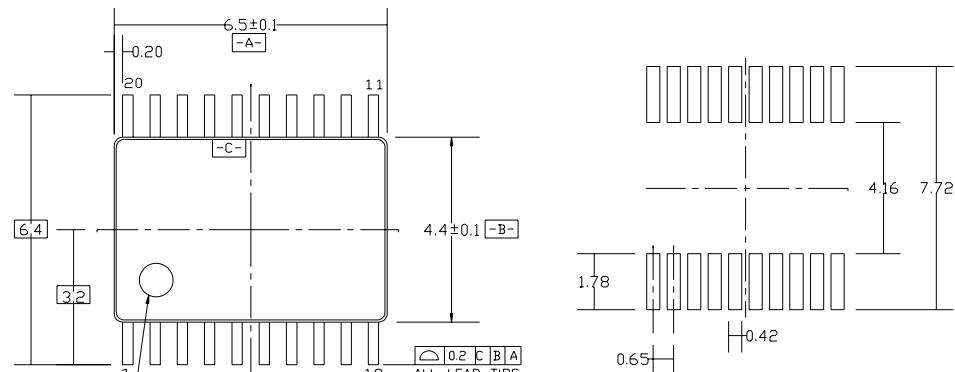


20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide  
Package Number M20B

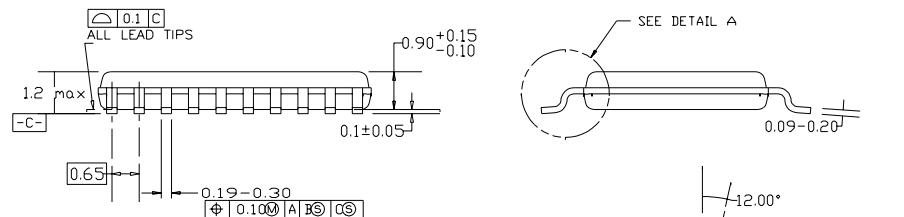


20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M20D

## **Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



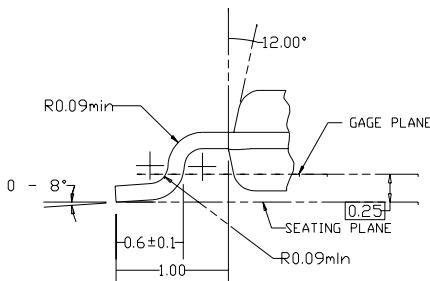
LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS

## NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

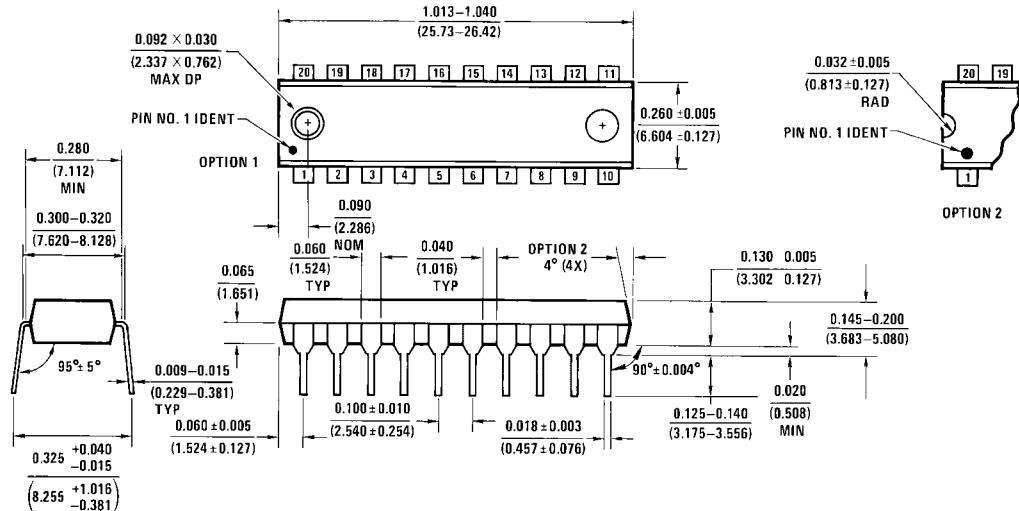


DETAIL A

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide  
Package Number MTC20**

74VHCT245A Octal Buffer/Line Driver with 3-STATE Outputs

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



N20A (REV G)

20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide  
Package Number N20A

**LIFE SUPPORT POLICY**

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

[www.fairchildsemi.com](http://www.fairchildsemi.com)